PMP8519RevA - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	1nF	Capacitor, Ceramic, 200V, X7R, 15%	1206	Std	Std
1	C2	560uF	Capacitor, Electrolytic, 10VDC, -55 to +125°C, 20%	10x12.5 mm	RHT1A561MDN1	Nichicon
1	C3	560uF	Capacitor, Electrolytic, 10VDC, -55 to +125°C, 20%	10x12.5 mm	RHT1A561MDN1	Nichicon
1	C4	4.7uF	Capacitor, Electrolytic, 400V, -25 to +85°C, 20%	10x16 mm	UVR2G4R7MPD	Nichicon
1	C5	4.7uF	Capacitor, Electrolytic, 400V, -25 to +85°C, 20%	10x16 mm	UVR2G4R7MPD	Nichicon
1	C6	open	Capacitor, Ceramic, 50V, X7R, 15%	805	Std	Std
1	C7	330nF	Capacitor, Ceramic, 50V, X7R, 15%	805	Std	Std
1	C8	1000pF	Capacitor, Ceramic Disk, 500VAC	0.720 inch	440LD10-R	Vishay
1	C9	open	Capacitor, Ceramic, 50V, X7R, 15%	805	Std	Std
1	C101	1uF	Capacitor, Ceramic, 10V, X5R, 15%	805	Std	Std
1	D1	MURS160	Diode, UltraFast Rectifier, 1A, 600V	DO-214AA, SMB	MURS160-13-F	Diodes Inc
1	D2	B340L	Diode, Schottky, 3A, 40V	SMB	B340LB	Diodes Inc
1	D3	RS1B	Diode, 1A, 100V	SMA	RS!B-13-F	Diodes Inc
1	D4	82V	Diode, Transient Voltage Suppressor, 600W, 82V	SMB	SMBJP6KE82A-TP	Micro Commercial Co
1	D5	HD06	Bridge Rectifier, 600V, 0.8A, Glass Passivated, SMD	MINI DIP4	HD04	Diodes, Inc
1	J1	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
1	J2	ED120/3DS	Terminal Block, 3-pin, 15-A, 5.1mm	0.60 x 0.35 inch	ED120/3DS	OST
1	L1	470uH	Inductor, Radial , 10%	5x6.5 mm	RLB0608-471KL	Bourns
1	Q1	STD2HNK60Z-1	MOSFET, N Chan, 600V, 2 A, 4.8 Ohm	IPAK	STD2HNK60Z-1	ST
1	R1	487	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R2	1.00k	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R3	10	10 ohm, TH Fusible Power Resistor, 3W	4522	PWR4522AS10R0JA	Bourns
1	R4	5.11M	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R5	5.11M	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R6	5.11M	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R7	68.1k	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R8	open	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R9	27.4k	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R10	1.30k	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R11	10	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R12	10.0k	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R13	1.5	Resistor, Chip, 1/4 watt, 1%	1206	Std	Std
1	R15	22.5	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	T1	750313684	Xfmr, Flyback, 20:4:1, 950uH	0.540 x 0.775 inch	750313684	Wuerth
1	TP1	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP2	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP4	5001	Test Point, Black, Thru Hole Color Keyed		5001	Keystone
1	U1	UCC28700	IC, Constant Voltage, Constant Current PWM With Primary Side Regulation	SOT23-6	UCC28700DBV	Texas Instruments

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